



Material Content Data Sheet



Sales Product Name	BTT6010-1EKB			Issued		12. September 2019		
MA#	MA005172000							
Package	PG-DSO-14-47			Weight*		151.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.709	3.12	3.12	31186	31186
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		458	
	non noble metal	iron	7439-89-6	1.383	0.92		9162	
	non noble metal	copper	7440-50-8	56.175	37.20	38.18	372005	381740
wire	non noble metal	copper	7440-50-8	0.760	0.50	0.50	5034	5034
encapsulation	organic material	carbon black	1333-86-4	0.165	0.11		1095	
	plastics	epoxy resin	-	7.603	5.04		50352	
	inorganic material	silicondioxide	60676-86-0	74.878	49.58	54.73	495859	547306
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16368	16368
plating	noble metal	silver	7440-22-4	1.470	0.97	0.97	9737	9737
glue	plastics	epoxy resin	-	0.228	0.15		1510	
	noble metal	silver	7440-22-4	1.075	0.71	0.86	7119	8629
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com